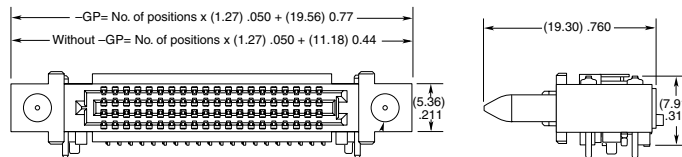


SERIES	POSITIONS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTIONS	"X"R
<b>SEAM</b> Right-Angle Terminal	-20 -30		<b>-L</b> = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	<b>-04</b> <b>-06</b> <b>-08</b> <b>-10</b>	<b>-1</b> = Tin/Lead Alloy Solder Charge <b>-2</b> = Lead-Free Solder Charge		<b>-GP</b> = Guide Post/Hole <b>-K</b> = Polyimide Film Pick & Place Pad <b>-LP</b> Latch Post (Available with SEAF in -06 Row with 30 positions only; Required for mating to SEAC)	<b>-TR</b> = Tape & Reel <b>-FR</b> = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
<b>SEAF</b> Right-Angle Socket	-40 -50		<b>-S</b> = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08 & -10 Row options require fixturing to process				

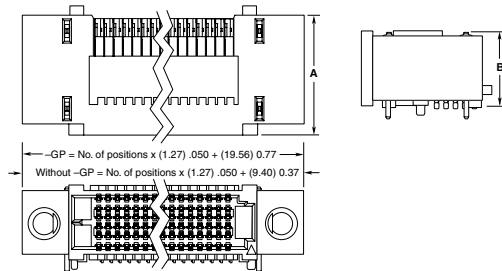
### SEAM-RA

Board Mates:  
SEAF, SEAF-RA, SEAFP



### SEAF-RA

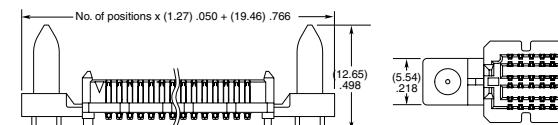
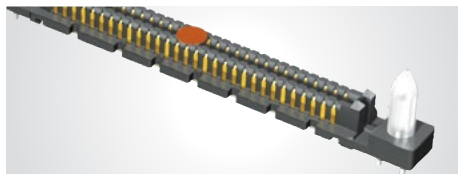
Board Mates:  
SEAM, SEAMP



NO. PINS PER ROW	A	B
-04	(13.77) .542	(7.91) .311
-06	(16.31) .642	(10.45) .411
-08	(18.85) .742	(12.99) .511
-10	(21.39) .842	(15.53) .611

View complete specifications at: [samtec.com?SEAM-RA](http://samtec.com?SEAM-RA) & [samtec.com?SEAF-RA](http://samtec.com?SEAF-RA)

SERIES	POSITIONS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	"X"R
<b>SEAM</b> Terminal with Guide post	-20, -30, -40, -50		<b>-L</b> = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail <b>-S</b> = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	<b>-04</b> <b>-06</b> <b>-08</b> <b>-10</b>	<b>-1</b> = Tin/Lead Alloy Solder Charge <b>-2</b> = Lead-Free Solder Charge				<b>-TR</b> = Tape & Reel <b>-FR</b> = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
<b>SEAM-GP</b> Board Mates: SEAF-RA-GP									



View complete specifications at: [samtec.com?SEAM](http://samtec.com?SEAM)

**Note:** Some lengths, styles and options are non-standard, non-returnable